

## 2017 CMPUG JULY SEMICON WEST MEETING – DRAFT AGENDA

**Topic: CMP Technology and Market Trends**

**Meeting Date:** July 12, 2017

**Time:** 12:30 pm - 4:00 pm

**Location:** PARC 55 Hotel  
55 Cyril Magnin Street, San Francisco, CA 94102

**Parking:** Nearby Public Parking

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**REGISTRATION: FREE, JUST SHOW UP!**

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### **Co-Chairs:**

**Ashwani Rawat, Intel Corp.**, [ashwani.k.rawat@intel.com](mailto:ashwani.k.rawat@intel.com)  
**Todd Buley, Dow Electronic Materials**, [tbuley@dow.com](mailto:tbuley@dow.com)

### **SPEAKERS/AGENDA**

- 12:30 - 12:40 PM      **Ashwani Rawat/Todd Buley**, Opening Remarks/Introductions
- 12:40 - 1:10 PM      **Len Jelinek, IHS Insights**, “Handset Demand Poised to Drive Second Half Surge in Semiconductors”
- 1:10 - 1:30 PM      **Michael White, Entegris**, “Challenges in Cleaning Tungsten and Cobalt for advanced node Post CMP and Post Etch Residue Removal Applications”
- 1:30 - 1:50 PM      **Matthew Bahr, Ara Philipossian, University of Arizona**, “Effect of Water Dilution and Method of Slurry Dispense on Silicon Dioxide Removal Rate for STI CMP using a Ceria Slurry”
- 1:50 - 2:10 PM      **Marty DeGroot, DOW Electronic Materials**, “State of CMP Materials”
- 2:10 - 2:30 PM      Coffee/Networking Break
- 2:30 - 2:50 PM      **Frank Tolic, AIM Photonics**, “CMP in Photonics Area”
- 2:50 - 3:10 PM      **Allan Biegaj, SCIA Systems**, “Sub-Aperture Ion-Milling based Planarization”
- 3:10 - 3:30 PM      **Mike Corbett, Linx Consulting**, “Developments in CMP and Impact on CMP Consumables”
- 3:30 - 3:50 PM      **Sanjay Baliga, SEMI**, “New Regulatory Requirements for Nanoscale Materials Under the U.S. Toxic Substances Control Act (TSCA)”
- 3:50 - 4:00 PM      **Ashwani Rawat/Todd Buley**, Concluding Remarks/Wrap-up

All presentations will be requested to be posted on the CMPUG Proceedings webpage approximately 1-2 weeks following the meeting.

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